
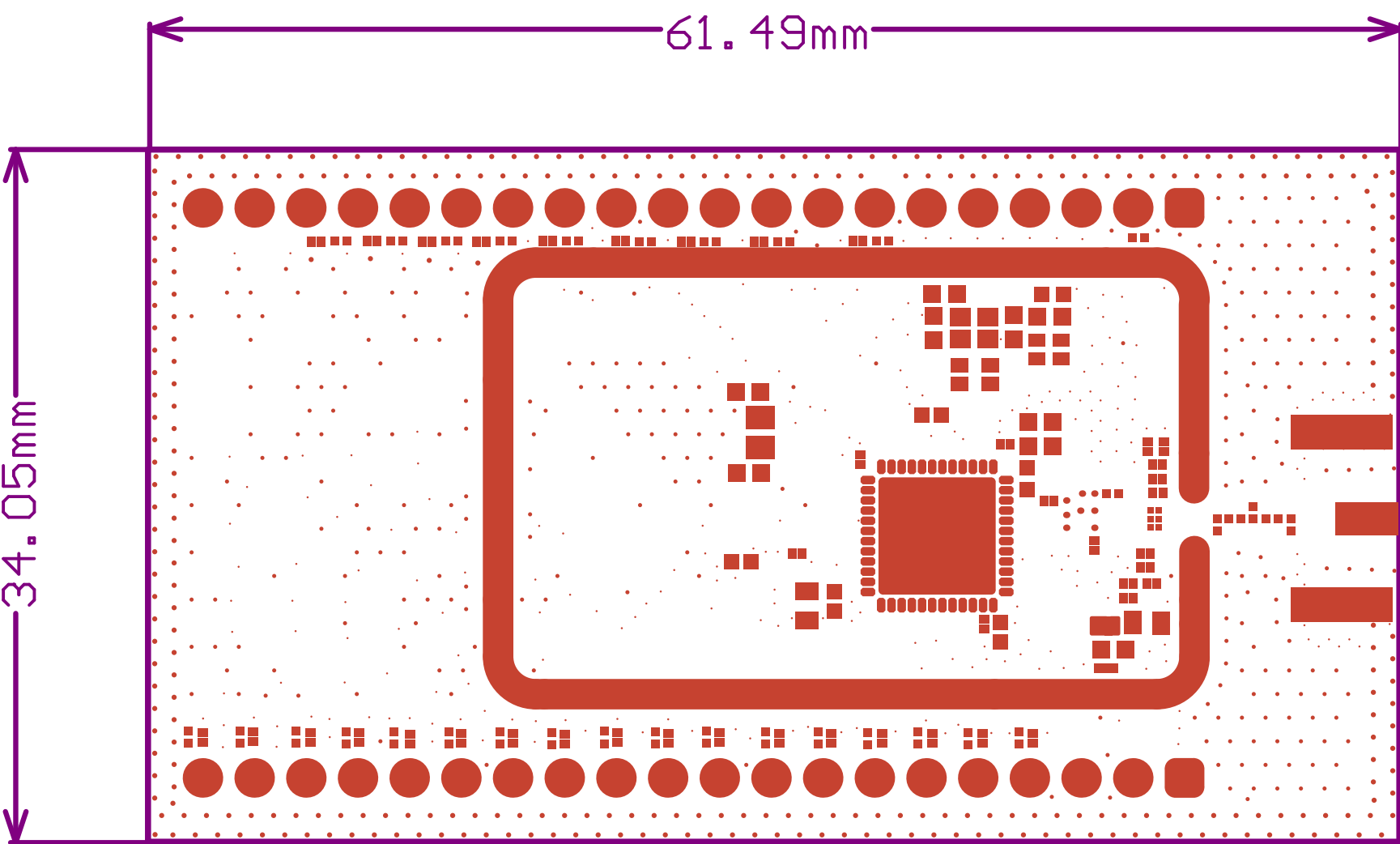

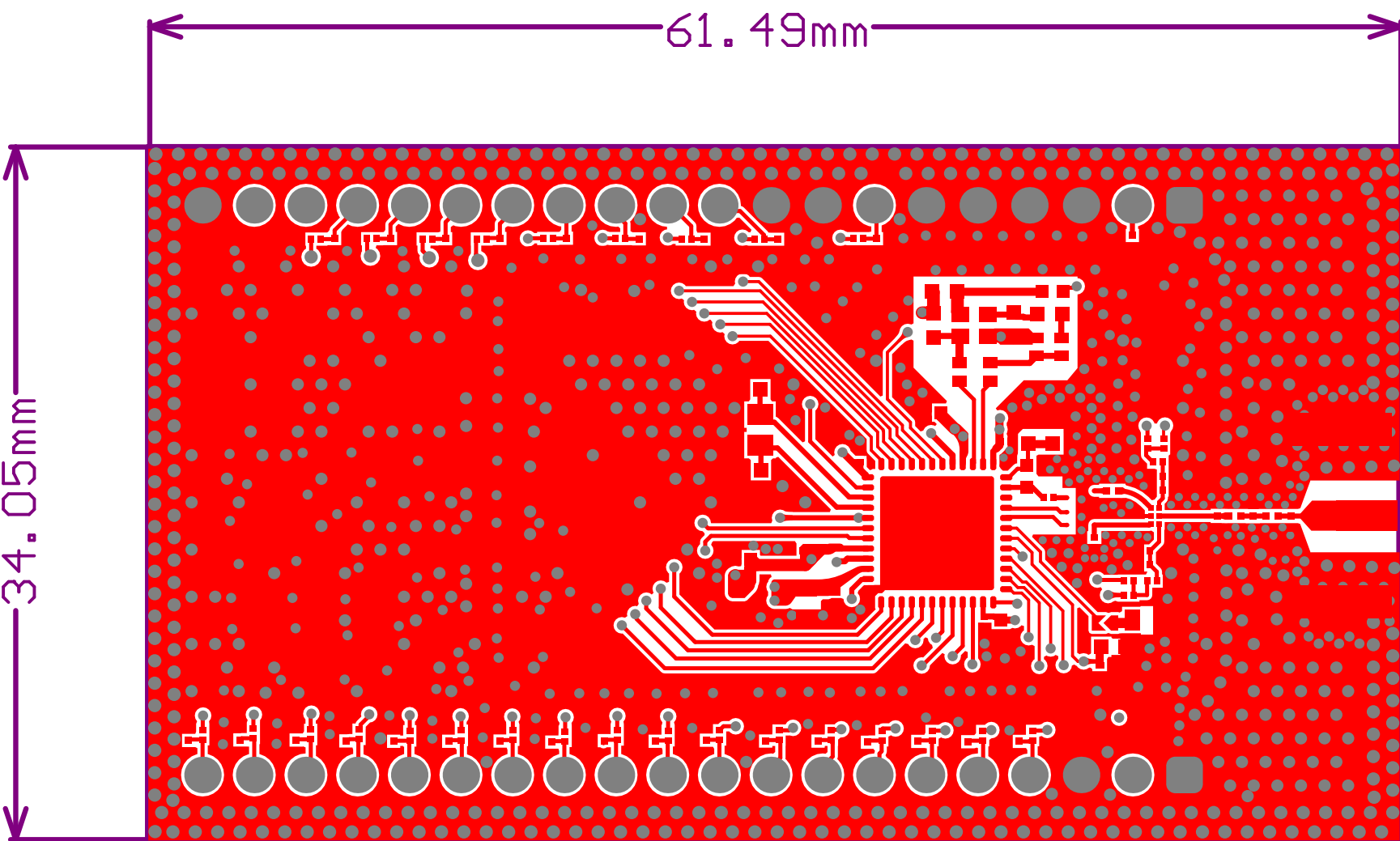



Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_HighPower		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1848_HP	
Date: June 2022	Rev: A	

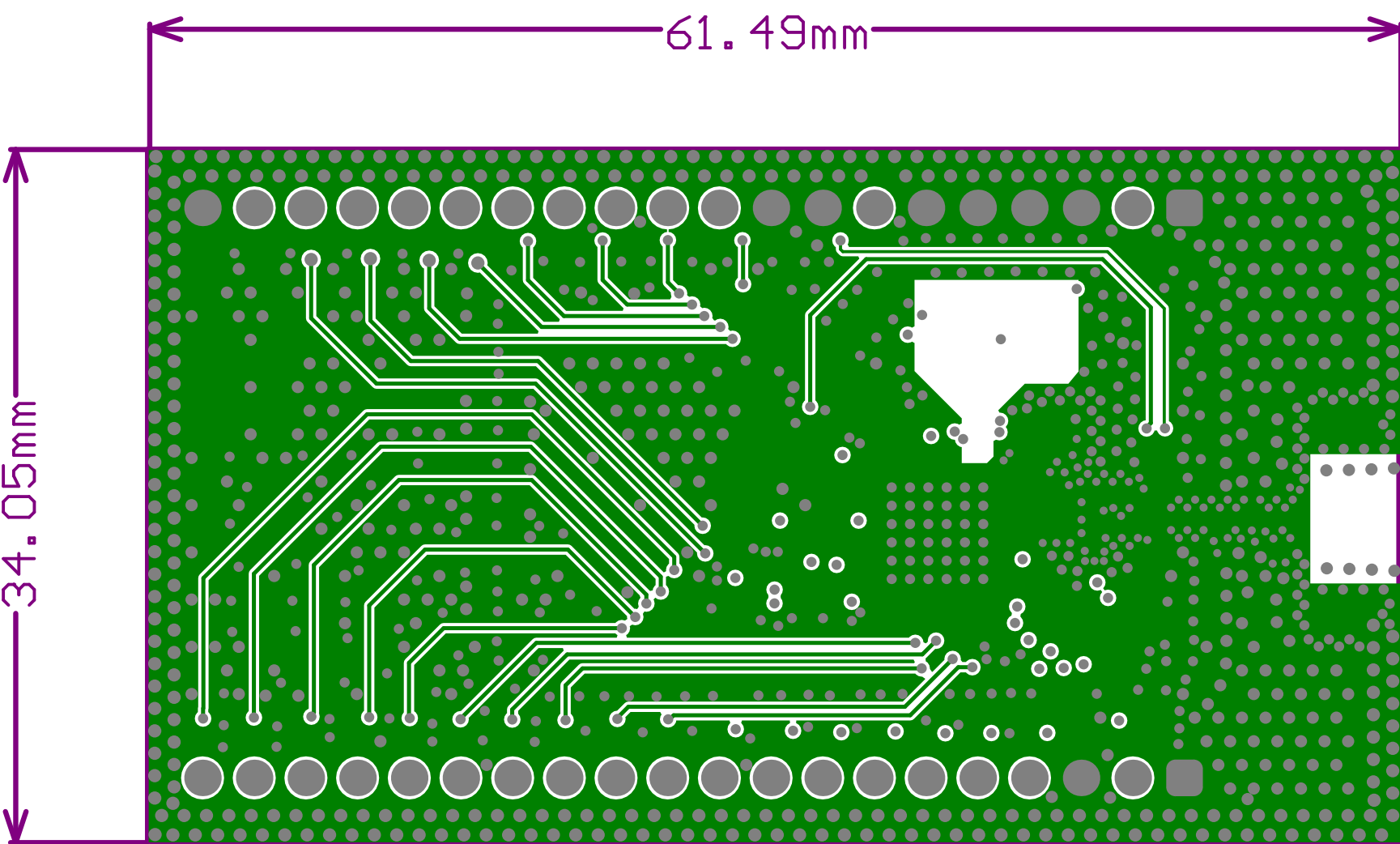



Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_HighPower		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1848_HP	
Date: June 2022	Rev: A	

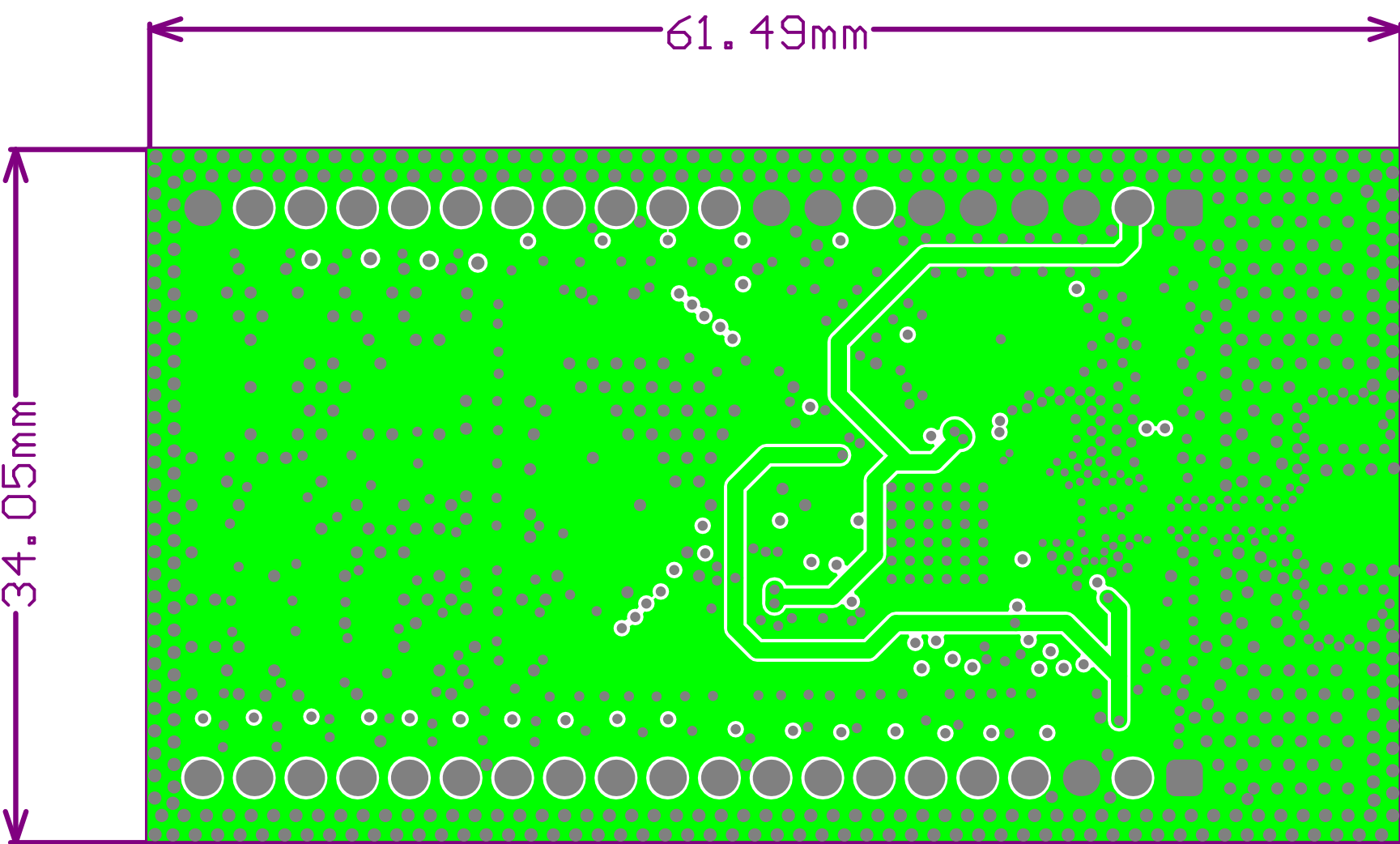



Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0.39mil	3.5
1	Top Layer		1.38mil	
	Dielectric 2	1 x 2116 + 1 x 106	6.30mil	3.7
2	MidLayer 1		0.69mil	
	Dielectric 1	FR-4	24.02mil	5
3	MidLayer 2		0.69mil	
	Dielectric 3	1 x 2116 + 1 x 106	6.30mil	3.7
4	Bottom Layer		1.38mil	
	Bottom Solder	Solder Resist	0.39mil	3.5
	Bottom Overlay			

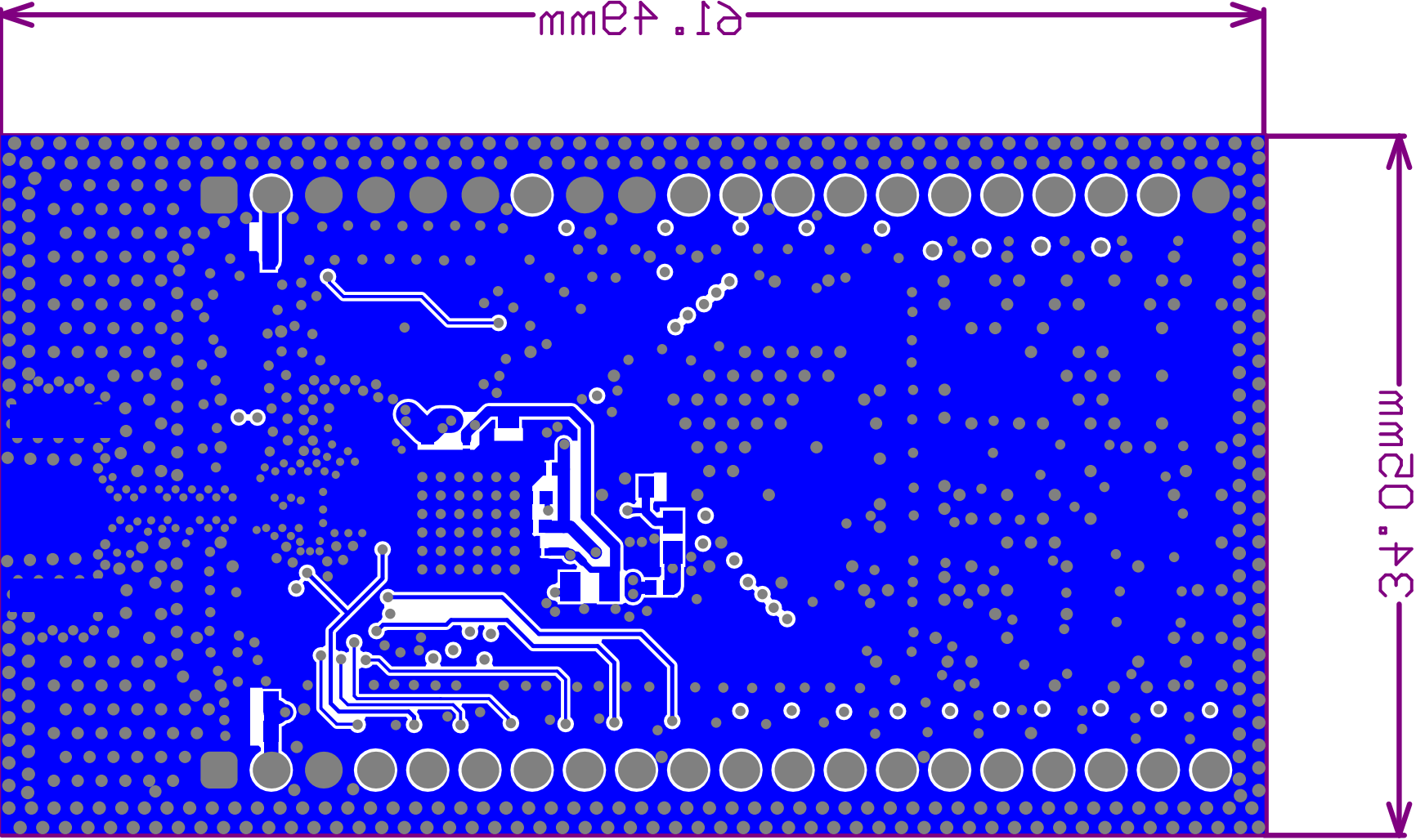
Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_HighPower		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1848_HP	
Date: June 2022	Rev: A	

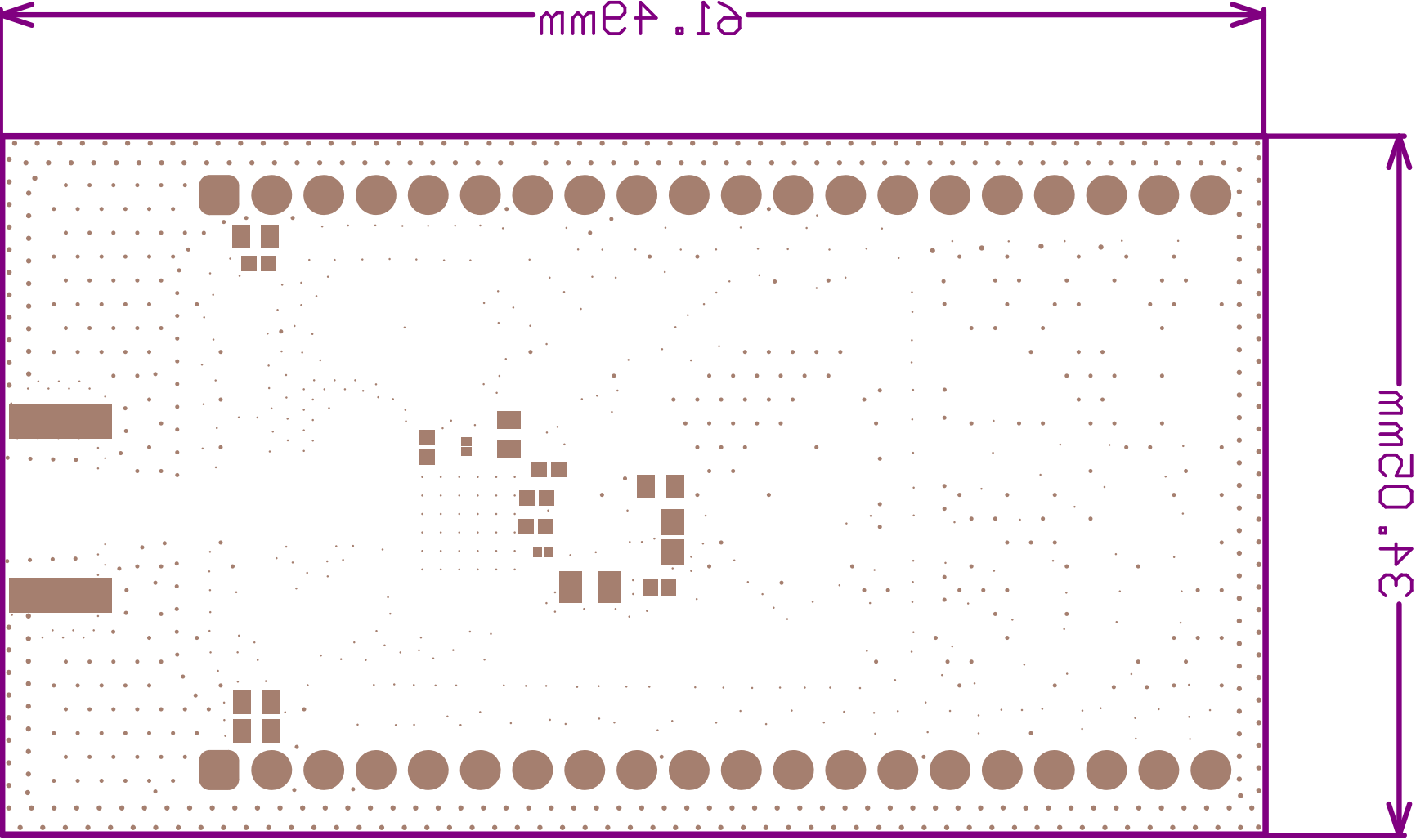


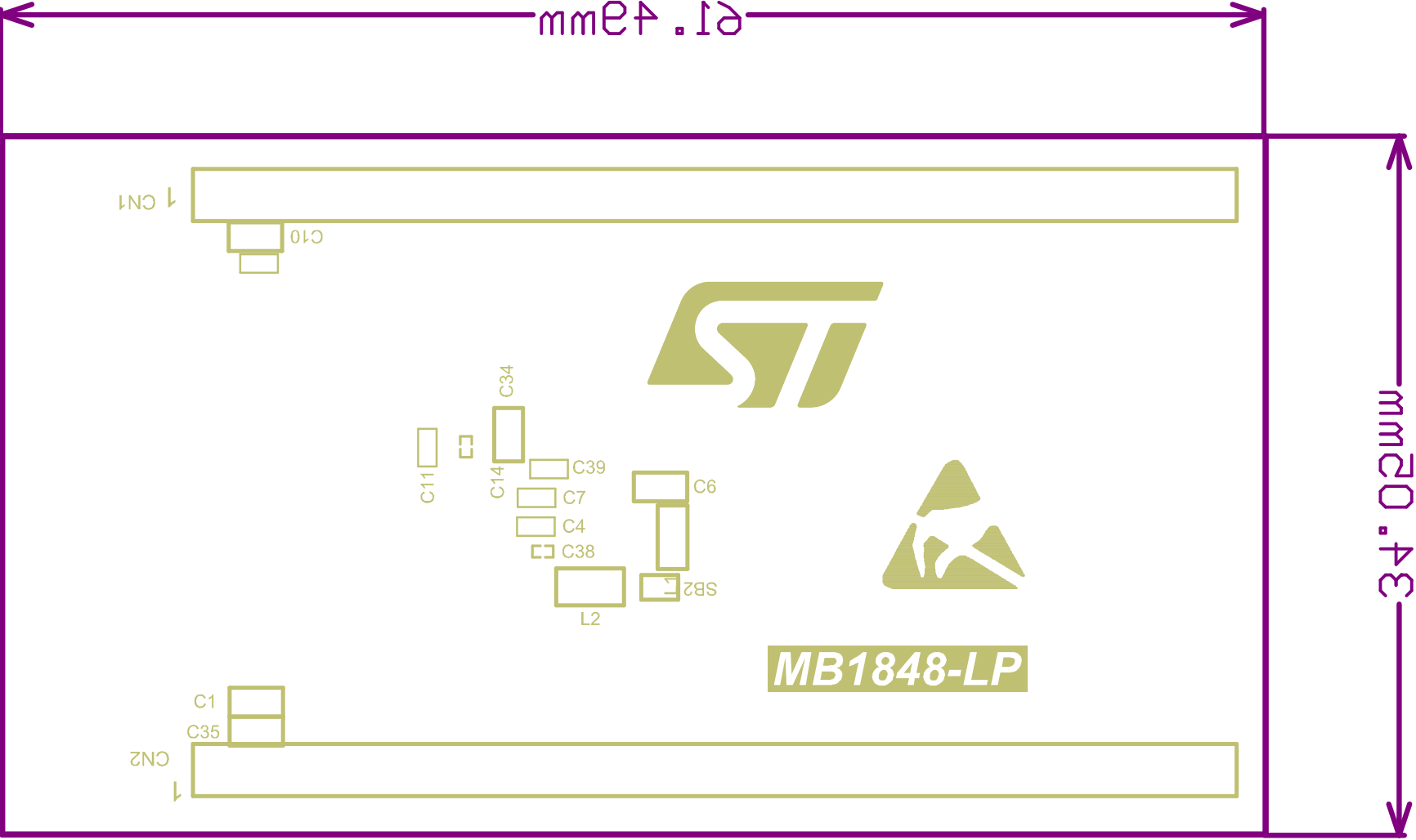
Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_HighPower		
Layer:	Gerber:	
Variant: [No Variations]	Ref: MB1848_HP	
Date: June 2022	Rev: A	



Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_HighPower		
Layer:	Gerber:	
Variant: [No Variations]	Ref: MB1848_HP	
Date: June 2022	Rev: A	







Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
✧	40	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
▽	1082	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)
	1122 Total							

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☒ GREEN

☐ WHITE

☒ ENIG

☐ HASL

☐ NO

☒ TG-170

☐ TG-150

☐ TG-140

☐ BLUE

☐ YELLOW

☐ IMMERSION SILVER

☐ HASL (PB-FREE)

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

☐ RED

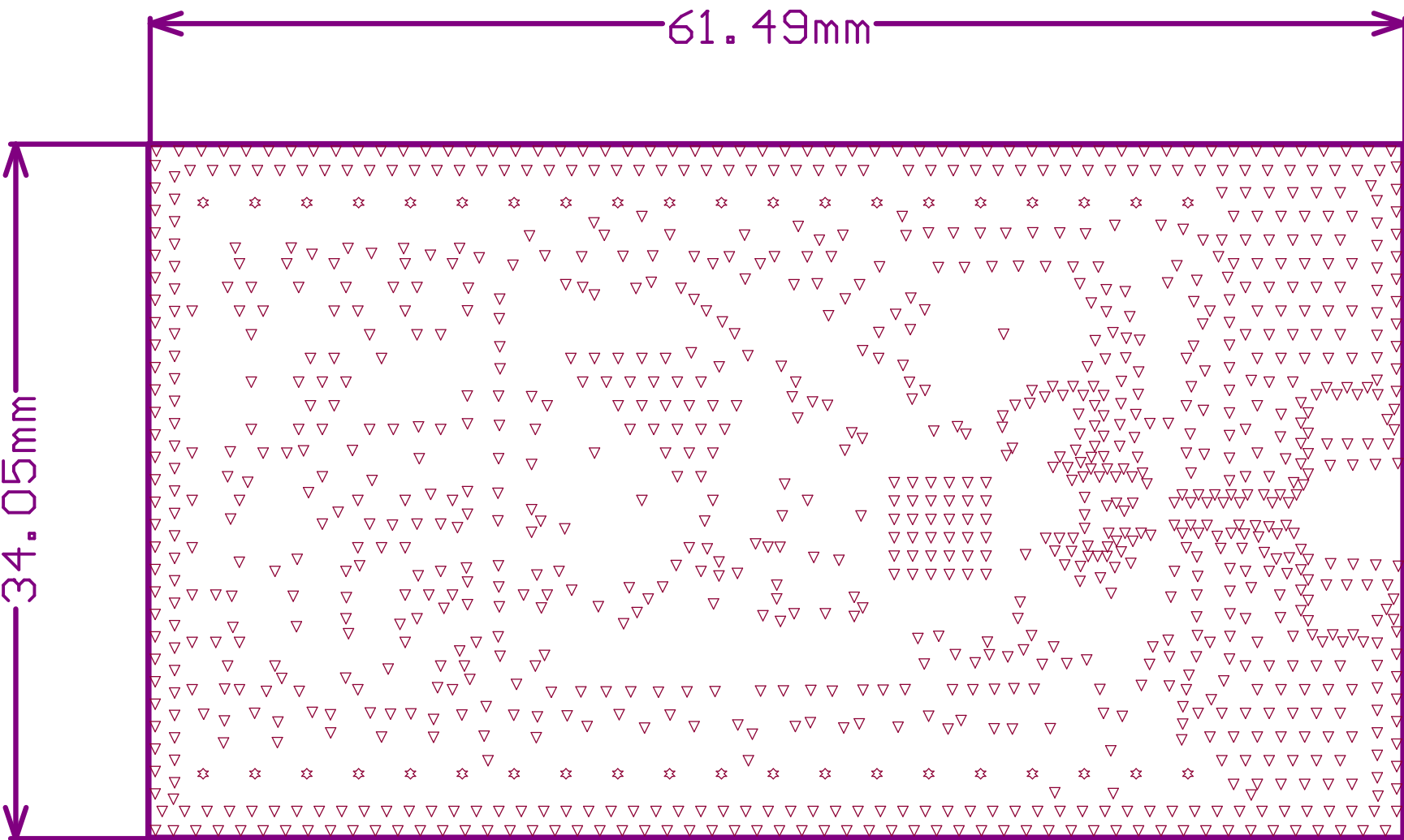
☐ BLACK


☐ IMMERSION TIN

☐ GOLDEN FINGER

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Project: STM32WL_QFN48_IPD_4Layers_IPD_TX_HighPower		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1848_HP	
Date: June 2022	Rev: A	

IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	9.84	6.89	50 ohm	NA	+/- 10%